EVERWIDE
Everwide Chemical Co.
http://www.everwide.com.tw/
No. 36, Dougong 6th Rd., Douliu City,
Yunlin County 64069, Taiwan
Tel:(886)5-557-4717
Email: service@everwide.com.tw

Technical Data Sheet

JB 334-13

One Component Epoxy Adhesive

Product Description

JB334-13 is a one component epoxy adhesive designed for electronic devices bonding. This resin is suited for curing between 100~110°C and exhibits high viscosity and excellent thixotropic. This product can be also controled flow and have sag resistance. This product offers good handling, chemical resistance and perfect surface gloss. The durability of this resin is very high levels and this resin can pass many environmental test experiments.

Features

1. This resin offers excellent chemical resistance and solvent resistance.
2. This product has high thixotropic index. It is able to hold the shape of resin without any failure and deformation.
3. This resin has excellent retention of electrical insulation properties under high humidity conditions.
4. The reactivity of this product is good at the temperature higher than 100°C.
5. This product complies to the 2011/65/EU RoHS regulations.
6. This product complies to chlorine < 900ppm, bromine < 900ppm, chlorine + bromine < 1500ppm.

Typical Uncured Properties

	JB334-13
Appearance	Liquid
Color	Red
Viscosity 25°C, S14 3rpm, cps	> 230,000
Viscosity 25°C, S14 0.3rpm, cps	> 1,700,000
Thixotropic Index	> 7

Typical Curing Properties

Pot Life 25°C, days	3
Through Cure Time 100°C, min	10

Direction of Use

1. It should be applied to a clean surface which is free of dirt, grease or mold release. In many cases, a simple solvent wipe is sufficient.
2. The package of this product which is refrigated in -40~-5°C can be brought to ambient conditions by allowing to stand at room temperature 14~34 °C for 1 to 2 hours. Do not loosen container cover before temperature equilibration.
3. Cure time on the really part will depend upon factors such as part geometry, materials to be bonded, bondline thickness and efficiency of the oven. Cure schedule should be confirmed with actual production parts and equipment.

Typical Cured Properties*1

Glass Transition Temp., °C	110
CTE*2 (<Tg), μm/m/ °C	40
CTE*2 (>Tg), μm/m/ °C	180
Durometer Hardness, Shore D	83
Water Absorption Ratio(25°C/24hr), %	0.33
Water Absorption Ratio(80°C/24hr), %	1.11
Water Absorption Ratio(97°C/1.5hr), %	0.49
Shear Strength Al vs. Al,kgf/cm^2	60
Volume Resistivity, ohm-cm	5*10^{15}
Surface Resistivity, ohm	5*10^{14}
Dielectric Constant, 100Hz	3.8

*1 Specimen Cure Condition：100°C / 10min
*2 CTE: Coefficient of Thermal Expansion

Storage and Shelf Life

This resin should be kept without any possibility of moisture and heat exposure. It should be storage at -40°C ~ -5°C before opening the containers. Shelf life of this product is eight months. Before using, it should place this product at 14~34°C for 1 to 2 hours. The properties will be changed when replace this product at room temperature for long time.

Caution

Some findings indicate a lack of potential for carcinogenicity with the compositions of this product by long term recurrent application to the skin. However, contact with skin is likely to produce mild transient reddening. It is important to remove adhesive from skin with soap and water thoroughly. this product is of moderate acute toxicity by swallowing. If swallowed, call a physician. Avoid contact with eyes. In case of contact, flush with water for at least 15 minutes and get medical attention immediately. For specific information on this product, consult the Material Safety Data Sheet.